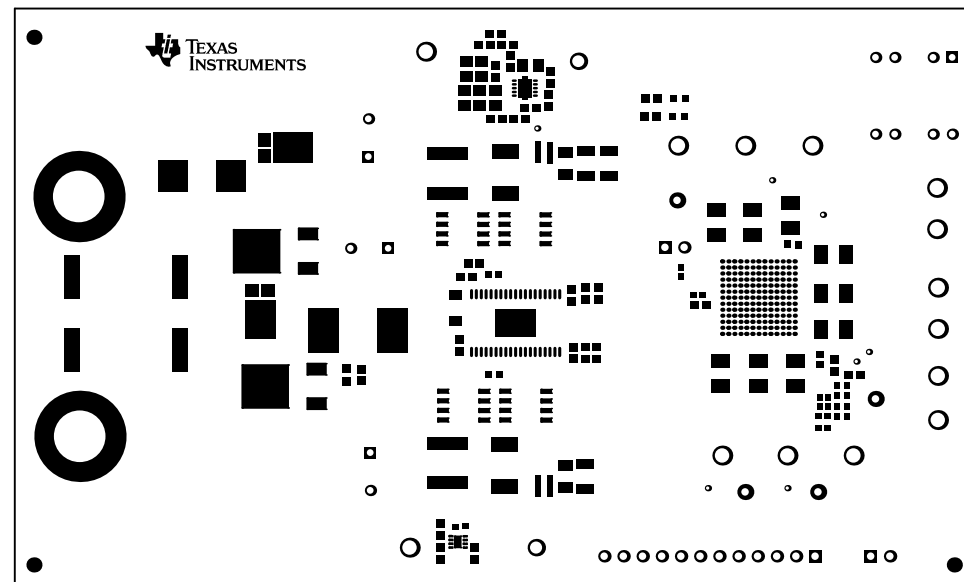
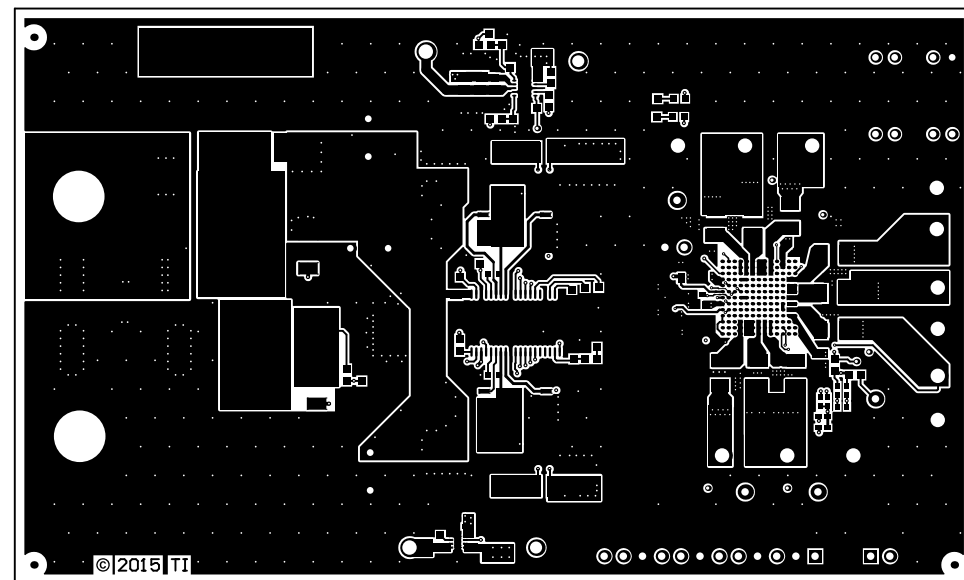


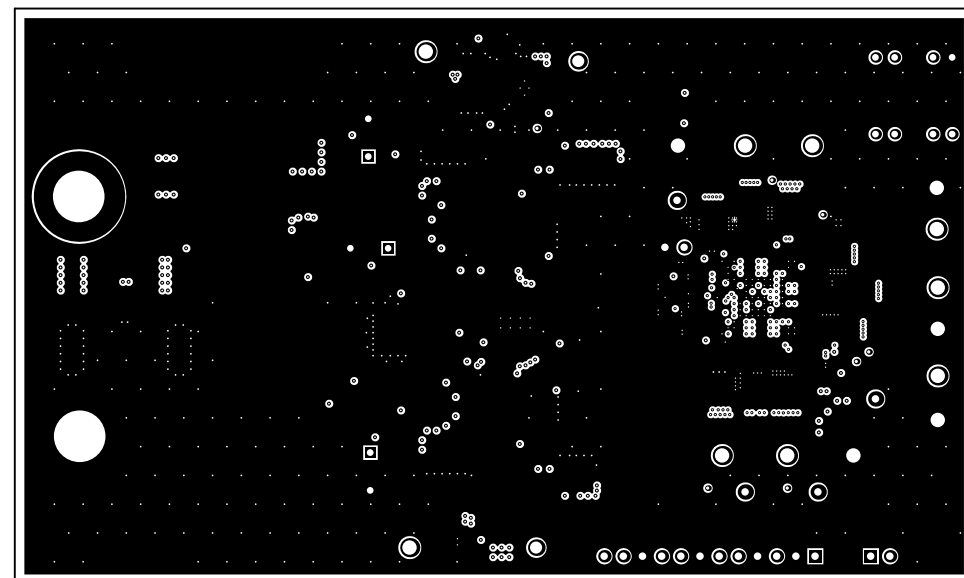
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00801	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 11/25/2015 2:22:08 PM	TEXAS INSTRUMENTS	



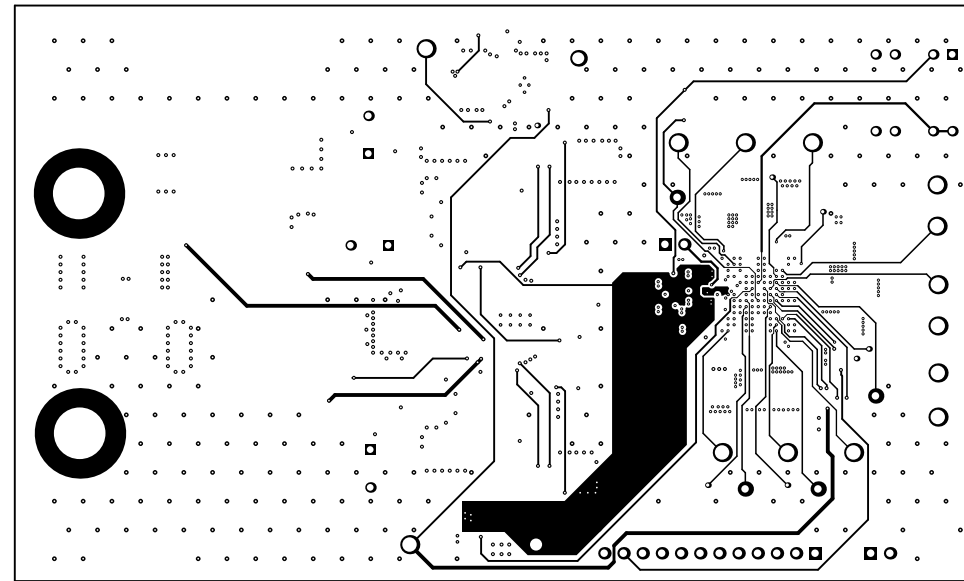
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00801	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 11/25/2015 2:22:10 PM	TEXAS INSTRUMENTS	



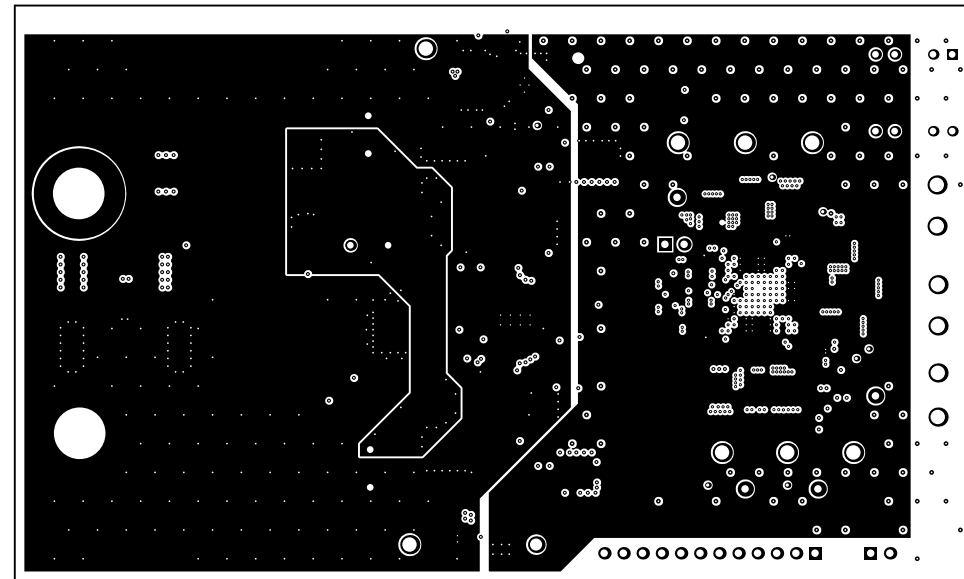
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00801	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 11/25/2015 2:22:13 PM	TEXAS INSTRUMENTS	



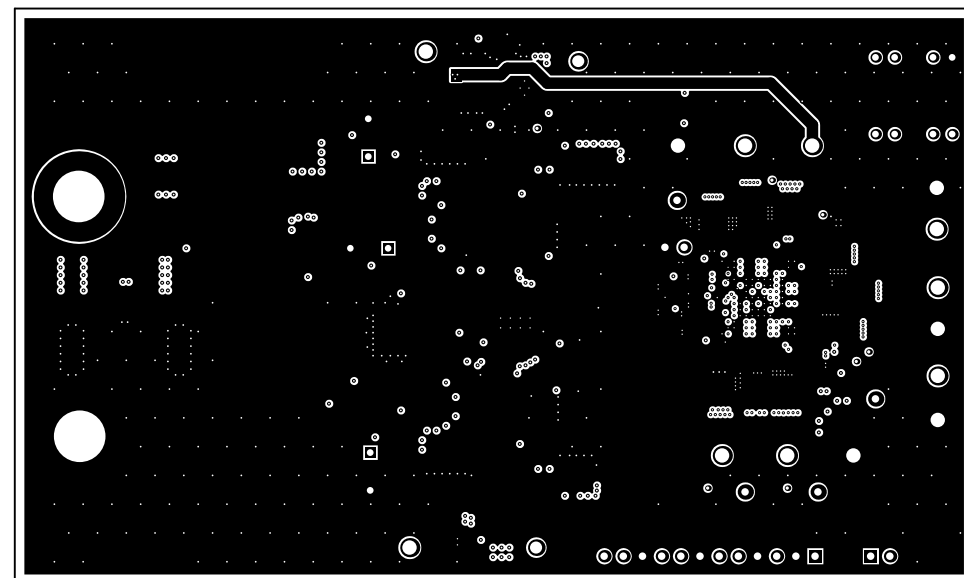
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00801	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Signal Layer 1			
PLOT NAME = Signal Layer 1	GENERATED : 11/25/2015 2:22:16 PM	TEXAS INSTRUMENTS	



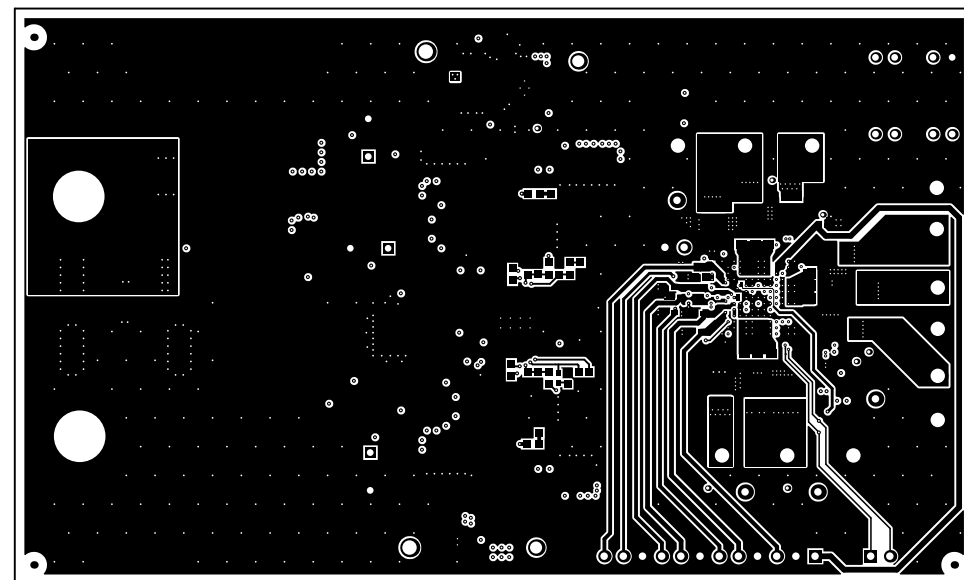
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00801	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Signal Layer 2			
PLOT NAME = Signal Layer 2	GENERATED : 11/25/2015 2:22:20 PM	TEXAS INSTRUMENTS	



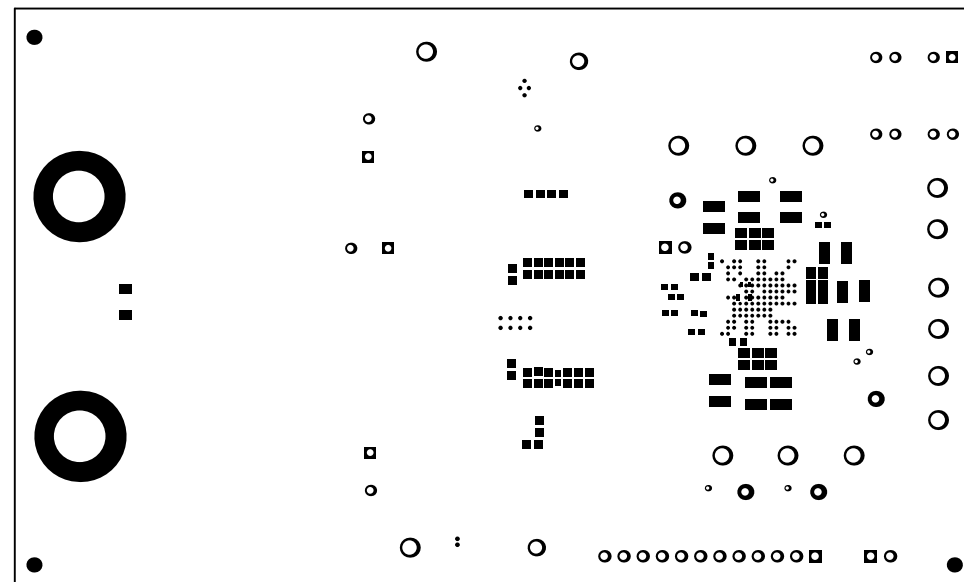
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00801	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Signal Layer 3			
PLOT NAME = Signal Layer 3	GENERATED : 11/25/2015 2:22:25 PM	TEXAS INSTRUMENTS	



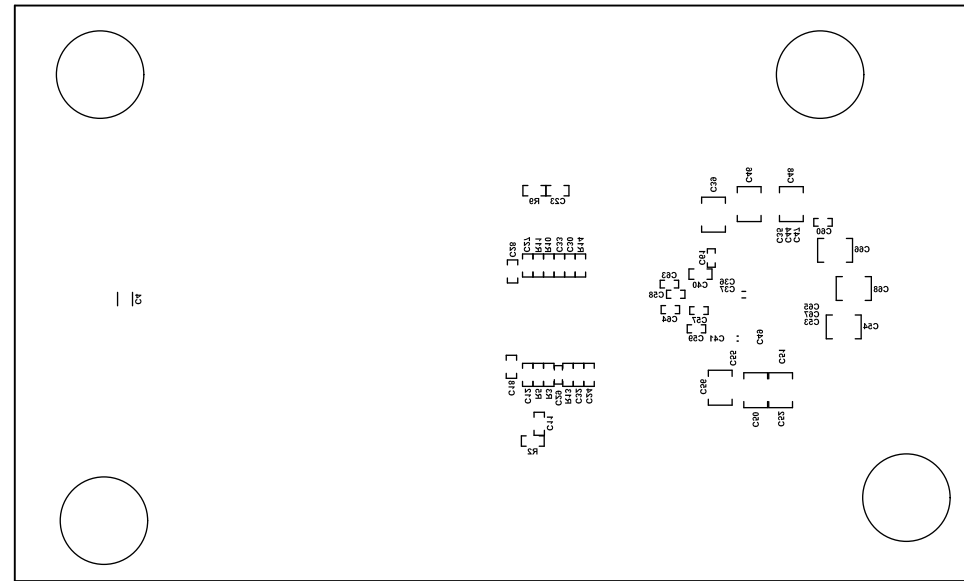
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00801	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Signal Layer 4			
PLOT NAME = Signal Layer 4	GENERATED : 11/25/2015 2:22:29 PM	TEXAS INSTRUMENTS	



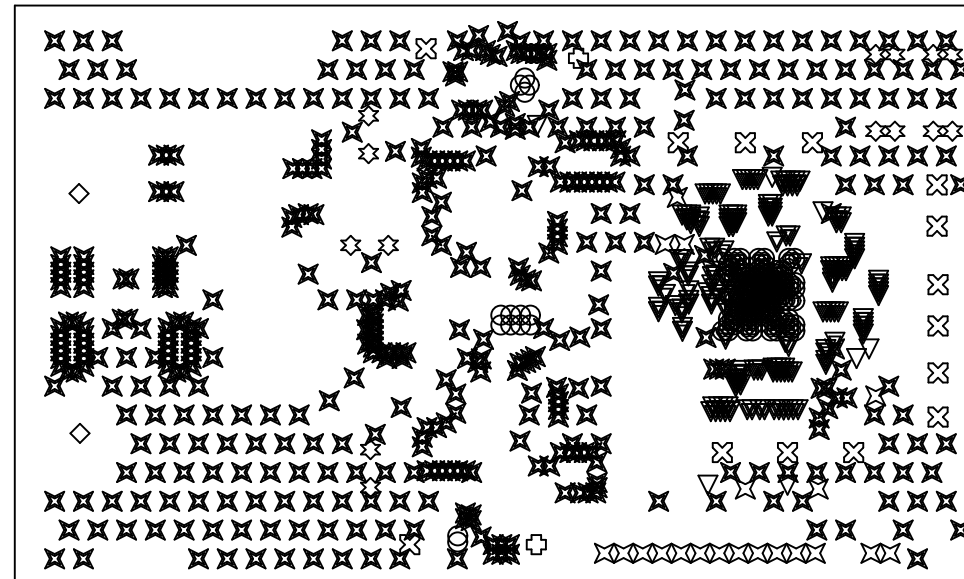
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00801	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 11/25/2015 2:22:35 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00801	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 11/25/2015 2:22:40 PM	TEXAS INSTRUMENTS	



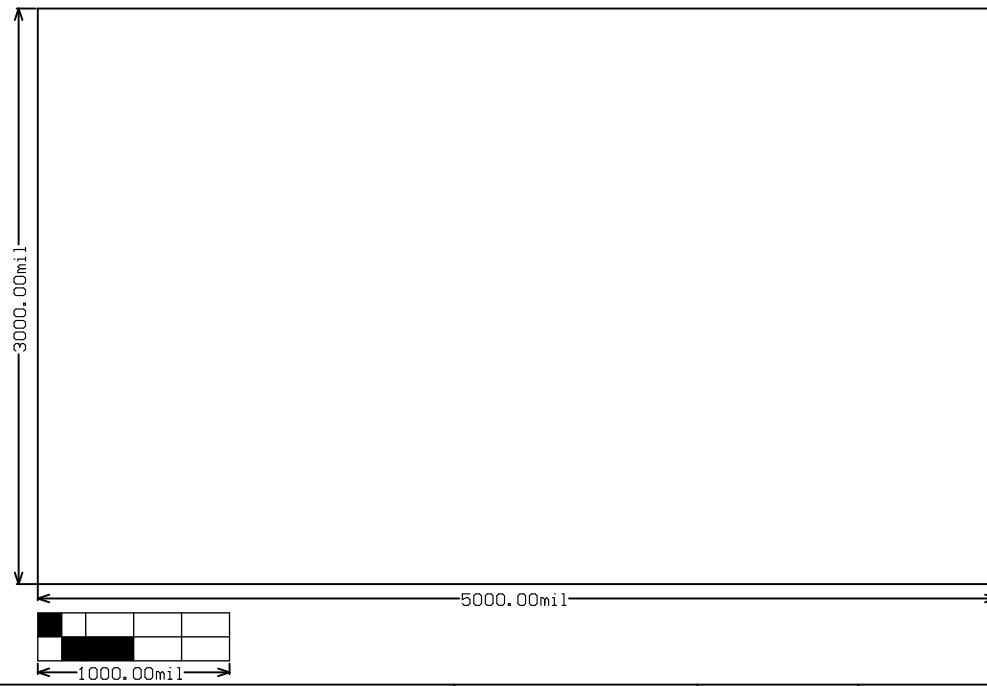
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00801	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 11/25/2015 2:22:47 PM	TEXAS INSTRUMENTS	



Symbol	Hit Count	Finished Hole Size	Plated	Hole Type
⊙	2	63.00mil (1.600mm)	PTH	Round
◇	2	270.00mil (6.858mm)	PTH	Round
▽	7	17.72mil (0.450mm)	PTH	Round
○	14	7.87mil (0.200mm)	PTH	Round
✱	14	35.43mil (0.900mm)	PTH	Round
⊗	14	76.00mil (1.930mm)	PTH	Round
⊗	20	40.00mil (1.016mm)	PTH	Round
●	104	7.80mil (0.198mm)	PTH	Round
▽	167	8.00mil (0.203mm)	PTH	Round
✱	472	10.00mil (0.254mm)	PTH	Round
	816 Total			

All 7.80MIL vias holes must be filled and plated closed

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00801	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 11/25/2015 2:22:53 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00801	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 11/25/2015 2:23:01 PM	TEXAS INSTRUMENTS	

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